## **UP04598**

## Silicon NPN epitaxial planar type

For high-frequency amplification (Tr1) For low-frequency amplification (Tr2)

#### ■ Features

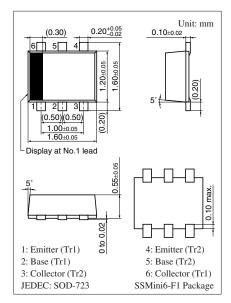
- Two elements incorporated into one package (Each transistor is separated)
- Reduction of the mounting area and assembly cost by one half

#### ■ Basic Part Number

• 2SC1047 + 2SC3311A

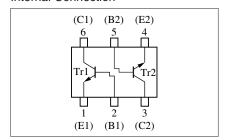
## ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter		Symbol	Rating	Unit
Tr1	Collector-base voltage (Emitter open)	V <sub>CBO</sub>	30	V
	Collector-emitter voltage (Base open)	V <sub>CEO</sub>	20	V
	Emitter-base voltage (Collector open)	V <sub>EBO</sub>	3	V
	Collector current	$I_C$	15	mA
Tr2	Collector-base voltage (Emitter open)	V <sub>CBO</sub>	60	V
	Collector-emitter voltage (Base open)	V <sub>CEO</sub>	50	V
	Emitter-base voltage (Collector open)	V <sub>EBO</sub>	7	V
	Collector current	$I_C$	100	mA
	Peak collector current	$I_{CP}$	200	mA
Overall	Total power dissipation	$P_{T}$	125	mW
	Junction temperature	$T_{j}$	125	°C
	Storage temperature	T <sub>stg</sub>	-55 to +125	°C



Marking Symbol: 3S

#### Internal Connection



## $\blacksquare$ Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

#### • Tr1

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	$I_C = 10 \ \mu A, I_E = 0$	30			V
Emitter-base voltage (Collector open)	$V_{EBO}$	$I_E = 10 \ \mu A, I_C = 0$	3			V
Forward current transfer ratio	$h_{FE}$	$V_{CB} = 6 \text{ V}, I_{E} = -1 \text{ mA}$	65		260	_
Base-emitter voltage	V <sub>BE</sub>	$V_{CB} = 6 \text{ V}, I_{E} = -1 \text{ mA}$		720		mV
Noise figure	NF	$V_{CB} = 6 \text{ V}, I_E = -1 \text{ mA}, f = 100 \text{ MHz}$		3.3		dB
Power gain	PG	$V_{CB} = 6 \text{ V}, I_E = -1 \text{ mA}, f = 100 \text{ MHz}$		24		dB
Reverse transfer capacitance	C <sub>re</sub>	$V_{CB} = 6 \text{ V}, I_E = -1 \text{ mA}, f = 10.7 \text{ MHz}$		0.8	1.0	pF
(Common emitter)						
Transition frequency	$f_T$	$V_{CB} = 6 \text{ V}, I_{E} = -1 \text{ mA}, f = 100 \text{ MHz}$	450	650		MHz

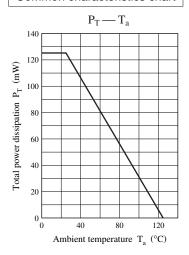
Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

#### • Tr2

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	$I_C = 10 \mu\text{A},  I_E = 0$	60			V
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	$I_C = 2 \text{ mA}, I_B = 0$	50			V
Emitter-base voltage (Collector open)	$V_{EBO}$	$I_E = 10 \ \mu A, I_C = 0$	7			V
Collector-base cutoff current (Emitter open)	$I_{CBO}$	$V_{CB} = 20 \text{ V}, I_{E} = 0$			0.1	μΑ
Collector-emitter cutoff current (Base open)	$I_{CEO}$	$V_{CE} = 10 \text{ V}, I_{B} = 0$			100	μΑ
Forward current transfer ratio	h <sub>FE1</sub>	$V_{CE} = 10 \text{ V}, I_{C} = 2 \text{ mA}$	160		460	_
	h <sub>FE2</sub> *	$V_{CE} = 2 \text{ V}, I_{C} = 100 \text{ mA}$	90			
Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	$I_C = 100 \text{ mA}, I_B = 10 \text{ mA}$		0.1	0.3	V
Transition frequency	$f_T$	$V_{CB} = 10 \text{ V}, I_E = -2 \text{ mA}, f = 200 \text{ MHz}$		150		MHz
Collector output capacitance	C <sub>ob</sub>	$V_{CB} = 10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		3.5		pF
(Common base, input open circuited)						

 $Note) \ 1. \ Measuring \ methods \ are \ based \ on \ JAPANESE \ INDUSTRIAL \ STANDARD \ JIS \ C \ 7030 \ measuring \ methods \ for \ transistors.$ 

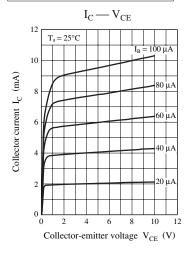
#### Common characteristics chart

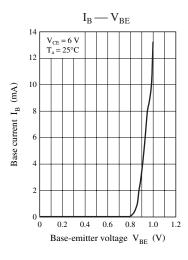


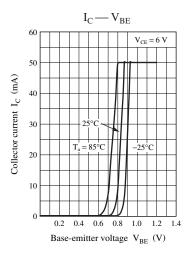
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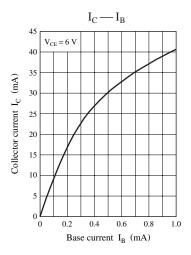
<sup>2. \*:</sup> Pulse measurement

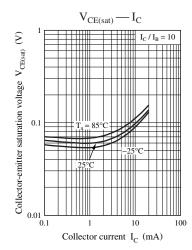
#### Characteristics charts of Tr1

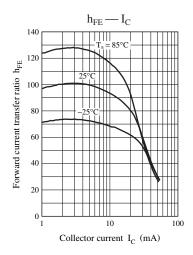


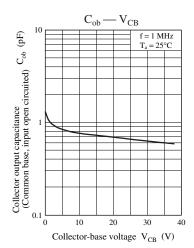




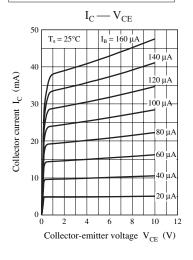


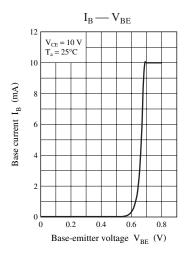


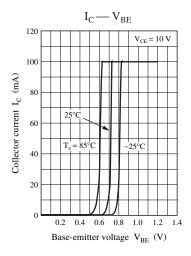


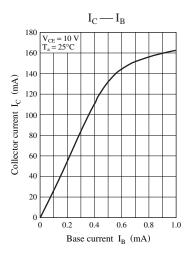


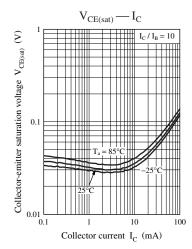
#### Characteristics charts of Tr2

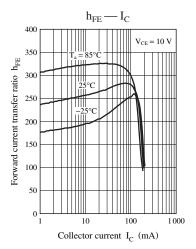


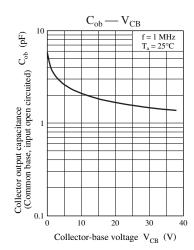












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